

L Number	Hits	Search Text	DB	Time stamp
1	356709	transmit\$6 near2 receiv\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/30 12:52
2	46066	code near2 transmit\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/30 13:14
3	77	copy near2 learn\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/30 12:53
4	10559	key and battery and (analog near2 digital)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/30 12:53
5	945	(key and battery and (analog near2 digital)) and rectifier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/30 13:16
6	537	(transmit\$6 near2 receiv\$6) and ((key and battery and (analog near2 digital)) and rectifier )	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/30 12:54
8	1	((transmit\$6 near2 receiv\$6) and ((key and battery and (analog near2 digital)) and rectifier )) and ((code near2 transmit\$6) and (copy near2 learn\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/30 12:54
7	7	(code near2 transmit\$6) and (copy near2 learn\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/30 12:54
9	11023	code and learn and transmit\$6 and receiv\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/30 13:01
10	749	(key and battery and (analog near2 digital)) and (code and learn and transmit\$6 and receiv\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/30 13:01
11	41	((key and battery and (analog near2 digital)) and (code and learn and transmit\$6 and receiv\$6)) and rectifier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/30 13:03
12	5218	train\$6 near (transmit\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/30 13:03
13	30	((key and battery and (analog near2 digital)) and (code and learn and transmit\$6 and receiv\$6)) and (train\$6 near (transmit\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/30 13:03

14	28	((key and battery and (analog near2 digital)) and (code and learn and transmit\$6 and receiv\$6)) and (train\$6 near (transmit\$6)) not ((key and battery and (analog near2 digital)) and (code and learn and transmit\$6 and receiv\$6)) and rectifier )	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 13:03
15	1137	(code near2 transmit\$6) and (key and battery and (analog near2 digital))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 13:14
16	191	(train\$6 near (transmit\$6)) and rectifier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 13:16
17	8	(code and learn and transmit\$6 and receiv\$6) and ((train\$6 near (transmit\$6)) and rectifier )	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 14:29
18	543	(340/825.22).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 14:29
19	72	(340/5.25).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 14:29
20	95	(340/825.61).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 14:30
21	1438	(340/825.69).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 14:30
22	578	(370/442).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 14:30
23	213	(370/478).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 14:30



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**1 Electromigration failure mechanism of Sn96.5Ag3.5 flip-chip solder bumps**

*Shao, T.L.; Chen, I.H.; Chih Chen;*  
Electronic Components and Technology, 2004. ECTC '04. Proceedings ,Volume: 1, June 1-4, 2004  
Pages:979 - 982

[\[Abstract\]](#)   [\[PDF Full-Text \(801KB\)\]](#)   IEEE CNF

**2 Electromigration induced failure in SnAg/sub 3.8/Cu/sub 0.7/ solder joints for flip chip technology**

*Hsu, Y.-C.; Shao, T.-L.; Chih Chen;*  
Electronic Materials and Packaging, 2002. Proceedings of the 4th International Symposium on , 4-6 Dec. 2002  
Pages:287 - 290

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